

LINEAR TECHNOLOGY MATERIALS DECLARATION

| 1t6554ign#trpbf                   |                                  | (Engineering Calculation) |            |                      |                               | SSOP                            |
|-----------------------------------|----------------------------------|---------------------------|------------|----------------------|-------------------------------|---------------------------------|
| (printed on: 2020-07-11 20:40:55) |                                  |                           |            |                      | TOTAL MASS (g) :              | 0.079453                        |
| COMPONENT MATERIAL                | VENDOR/ INDUSTRY NAMES           | CONSTITUENT NAME          | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. |
| Active Device                     | Linear Technology                | Silicon (Si)              | 7440-21-3  | 0.001175             | 1000000                       | 14788.6035156                   |
| Die Coat                          | Dow Corning                      | Silicone                  | 69430-27-9 | 0.000000             | 0                             | 0                               |
| Lead Frame                        | Cu                               | Copper (Cu)               | 7440-50-8  | 0.029933             | 975000                        | 376738.09375                    |
|                                   |                                  | Iron (Fe)                 | 7439-89-6  | 0.000737             | 24000                         | 9275.91601562                   |
|                                   |                                  | Phosphorus (P)            | 7723-14-0  | 0.000009             | 300                           | 113.274414062                   |
|                                   |                                  | Zinc (Zn)                 | 7440-66-6  | 0.000021             | 700                           | 264.306945801                   |
|                                   |                                  | Nickel (Ni)               | 7440-02-0  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Silicon (Si)              | 7440-21-3  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Magnesium (Mg)            | 7439-95-4  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Lead Frame Total:         |            | 0.030700             | 1000000                       | 386391.625                      |
| Plating                           | PMI                              | Exter. Plating Pb         | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Exter. Plating Sn         | 7440-31-5  | 0.002272             | 1000000                       | 28596.5039062                   |
|                                   |                                  | External Plating Total:   |            | 0.002272             | 1000000                       | 28596.5039062                   |
|                                   |                                  | Inter. Plating Ni         | 7440-02-0  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Inter. Plating Ag         | 7440-22-4  | 0.000246             | 1000000                       | 3096.16723633                   |
|                                   |                                  | Internal Plating Total:   |            | 0.000246             | 1000000                       | 3096.16723633                   |
| Die Attach                        | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag)               | 7440-22-4  | 0.000488             | 750000                        | 6141.98974609                   |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Lead (Pb)                 | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.000000             | 0                             | 0                               |
|                                   |                                  | Indium (In)               | 7440-74-6  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Metal Oxide               |            | 0.000000             | 0                             | 0                               |
|                                   |                                  | Antimony (Sb)             | 7440-36-0  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Resin (EP)                |            | 0.000163             | 250000                        | 2051.52563477                   |
|                                   |                                  | Die Attach Total:         |            | 0.000651             | 1000000                       | 8193.51660156                   |
| Encapsulation                     | MULTI-AROMATIC RESIN Br/Sb FREE  | Resin (EP)                |            | 0.006623             | 150000                        | 83357.375                       |
|                                   |                                  | Bromine (Br)              | 40039-93-8 | 0.000000             | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.036203             | 820000                        | 455652.625                      |
|                                   |                                  | Antimony Trioxide (Sb2O3) | 1309-64-4  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Metal Hydroxide           |            | 0.001104             | 25000                         | 13894.9951172                   |
|                                   |                                  | Carbon Black (C)          | 1333-86-4  | 0.000221             | 5000                          | 2781.51586914                   |
|                                   |                                  | Encapsulation Total:      |            | 0.044151             | 1000000                       | 555686.5625                     |
| Bond Wire Estimated               | AFW/TANAKA/ Kn                   | Gold (Au)                 | 7440-57-5  | 0.000258             | 1000000                       | 3247.19946289                   |
|                                   |                                  |                           |            |                      | TOTAL MASS (g) :              | 0.079453                        |